

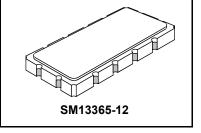


• Precision IF SAW Filter

- Hermetic 13.3 x 6.5 mm Surface-mount Case
- Complies with Directive 2002/95/EC (RoHS)
- Moisture Sensitivity Level: 1

140 MHz SAW Filter

SF2189A



Absolute Maximum Ratings

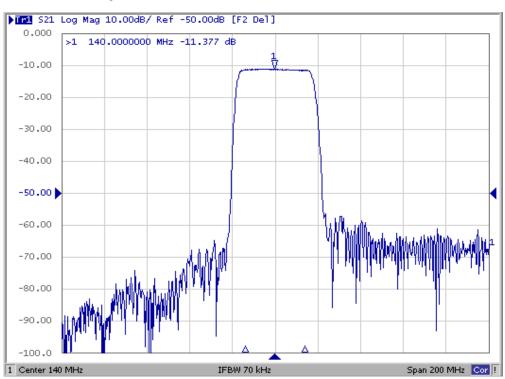
Rating	Value	Units	
Maximum Incident Power in Passband	+10	dBm	
Maximum DC Voltage between any Two Terminals	3	VDC	
Storage Temperature Range in Tape and Reel	-40 to +85 °C		
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s		

Electrical Characteristics

Characteristic	Sym	Notes	Min	Тур	Max	Units
Center Frequency	F _C			140		MHz
Minimum Insertion Loss	IL _{MIN}			11.3	13.0	dB
1 dB Bandwidth	BW ₁		30.0	33.0		MHz
3 dB Bandwidth	BW ₃		32.0	35.0		MHz
35 dB Bandwidth	BW ₃₅			42.4	44.0	MHz
Passband Amplitude Ripple, 80% of 3 dB Bandwidth				0.6	1.2	dB _{P-P}
Passband Group Delay Ripple, 80% of 3 dB Bandwidth				50	120	ns _{P-P}
Passband Absolute Group Delay				0.55		μs
Passband Phase Linearity, 80% of 3 dB Bandwidth				5	14	deg _{P-P}
Specification Temperature Range			-20		+80	°C
Operable Temperature Range			-45		+125	°C
Frequency Temperature Coefficient				-94		ppm/°C
Source Impedance				50		ohm
Load Impedance				50		ohm
Case Style		SM133	365-12 13.3 x	6.5 mm Nomin	al Footprint	
Lid Symbolization (YY = year, WW = week, S = Shift, ## = Sequence Code)		SF2189A <u>YYWWS##</u>				

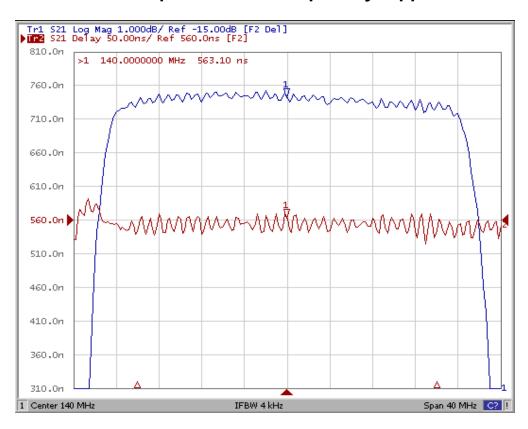
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

- 1. The design, manufacturing process, and specifications of this device are subject to change.
- 2. US or International patents may apply.
- 3. RoHS compliant from the first date of manufacture.

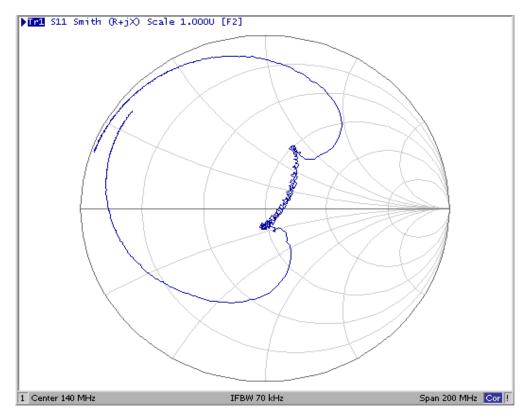


SF2189A Filter Response

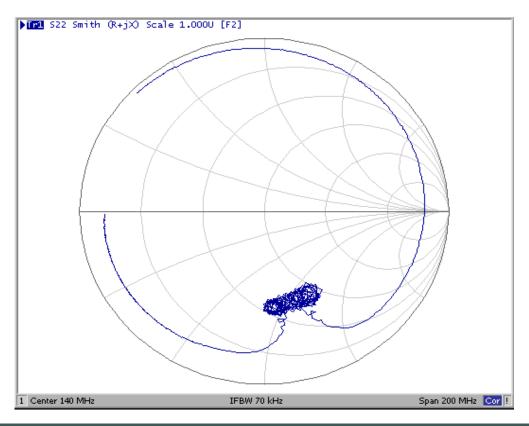
SF2189A Passband Amplitude and Group Delay Ripple



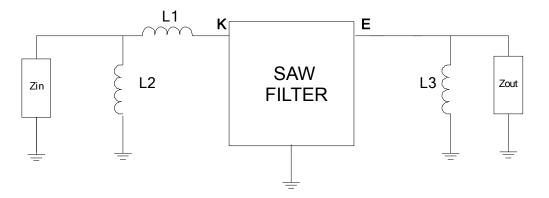
SF2189A Input Impedance (K Port)



SF2189A Output Impedance (E Port)

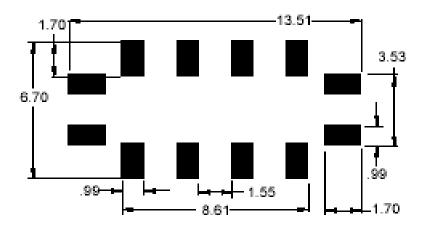


SF2189A 50 ohm Matching Network



L1 = 10 nH, L2 = 27 nH, L3 = 68 nH

SF2189A PCB Pad Layout

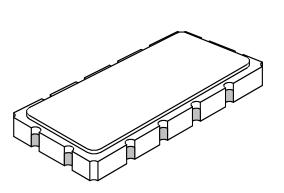


SM13365-12 Case

12-Terminal Ceramic Surface-Mount Case

13.3 x 6.5 mm Nominal Footprint

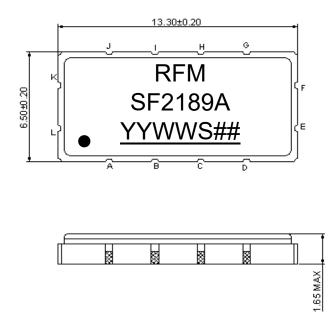
Case Dimensions

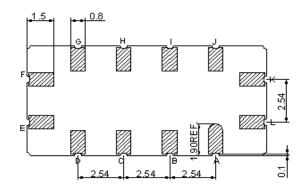


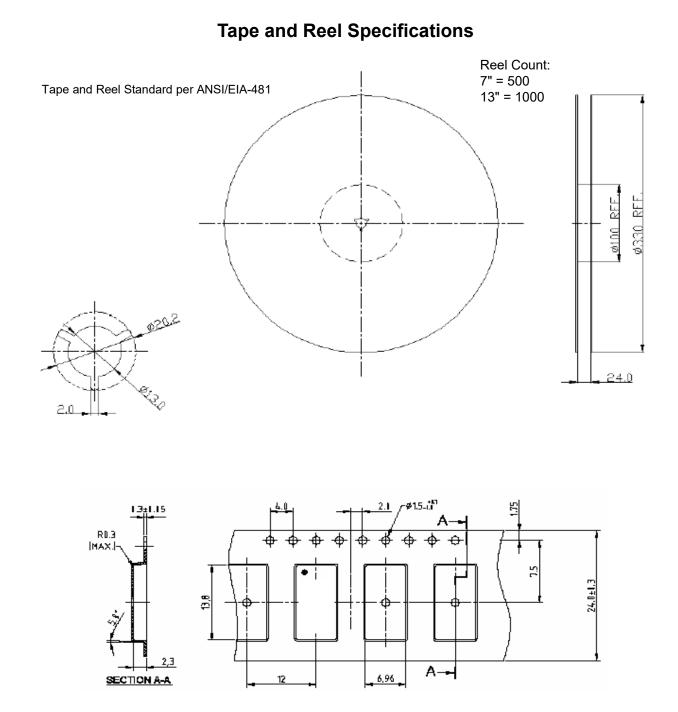
Dimension	mm Inches					
	Min	Nom	Max	Min	Nom	Max
Α	13.08	13.31	13.60	0.515	0.524	0.535
В	6.27	6.50	6.80	0.247	0.256	0.268
С		1.91	2.00		0.075	0.079
D		1.50			0.059	
E		0.79			0.031	
н		1.0			0.039	
Р		2.54			0.100	
Electrical Connections						
Connection			Terminals			

Connection	Terminals
Input	К
Output	E
Case Ground	All others

Materials				
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel			
Lid Plating	2.0 to 3.0 µm Nickel			
Body	Al ₂ O ₃ Ceramic			







Recommended Reflow Profile

- 1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
- 2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
- 3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
- 4. Time: 5 times maximum.

